

4V Drive Nch MOSFET

RSD080N06

● Structure

Silicon N-channel MOSFET

● Features

- 1) Low on-resistance.
- 2) 4V drive.
- 3) High power package(CPT3).

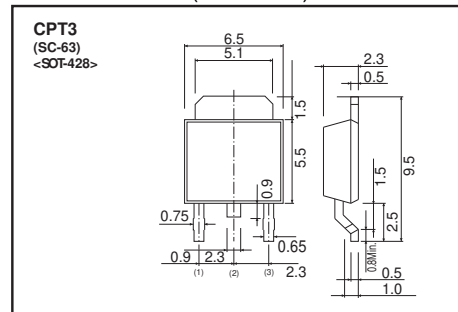
● Application

Switching

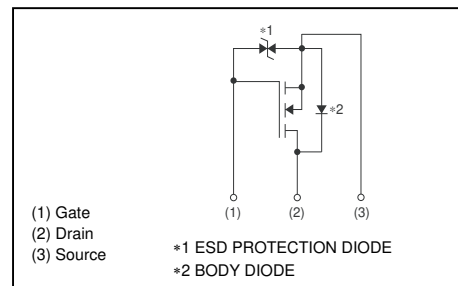
● Packaging specifications

| Type | Package | Taping |
|-----------|------------------------------|--------|
| | Code | TL |
| | Basic ordering unit (pieces) | 2500 |
| RSD080N06 | | ○ |

● Dimensions (Unit : mm)



● Inner circuit



● Absolute maximum ratings (Ta = 25°C)

| Parameter | Symbol | Limits | Unit |
|------------------------------|------------|-------------|------------|
| Drain-source voltage | V_{DSS} | 60 | V |
| Gate-source voltage | V_{GSS} | ± 20 | V |
| Drain current | Continuous | I_D | ± 8 A |
| | Pulsed | I_{DP} *1 | ± 16 A |
| Source current (Body Diode) | Continuous | I_S | 8 A |
| | Pulsed | I_{SP} *1 | 16 A |
| Power dissipation | P_D *2 | 15 | W |
| Channel temperature | T_{ch} | 150 | °C |
| Range of storage temperature | T_{stg} | -55 to +150 | °C |

*1 $P_w \leq 10 \mu s$, Duty cycle $\leq 1\%$

*2 $T_C = 25^\circ C$

● Thermal resistance

| Parameter | Symbol | Limits | Unit |
|-----------------|------------------|--------|--------|
| Channel to Case | $R_{th(ch-c)}$ * | 8.33 | °C / W |

* $T_C = 25^\circ C$

● Electrical characteristics (Ta = 25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|----------------|------|------|------|------|-----------------------------|
| Gate-source leakage | I_{GSS} | - | - | ±10 | μA | $V_{GS}=\pm 20V, V_{DS}=0V$ |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 60 | - | - | V | $I_D=1mA, V_{GS}=0V$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 1 | μA | $V_{DS}=60V, V_{GS}=0V$ |
| Gate threshold voltage | $V_{GS(th)}$ | 1.0 | - | 2.5 | V | $V_{DS}=10V, I_D=1mA$ |
| Static drain-source on-state resistance | $R_{DS(on)}^*$ | - | 57 | 80 | mΩ | $I_D=8A, V_{GS}=10V$ |
| | | - | 70 | 98 | | $I_D=8A, V_{GS}=4.5V$ |
| | | - | 78 | 109 | | $I_D=8A, V_{GS}=4.0V$ |
| Forward transfer admittance | $ Y_{fs} ^*$ | 4.8 | - | - | S | $V_{DS}=10V, I_D=8A$ |
| Input capacitance | C_{iss} | - | 380 | - | pF | $V_{DS}=10V$ |
| Output capacitance | C_{oss} | - | 90 | - | pF | $V_{GS}=0V$ |
| Reverse transfer capacitance | C_{rss} | - | 50 | - | pF | $f=1MHz$ |
| Turn-on delay time | $t_{d(on)}^*$ | - | 9 | - | ns | $V_{DD}=30V, I_D=4A$ |
| Rise time | t_r^* | - | 13 | - | ns | $V_{GS}=10V$ |
| Turn-off delay time | $t_{d(off)}^*$ | - | 30 | - | ns | $R_L=7.5\Omega$ |
| Fall time | t_f^* | - | 10 | - | ns | $R_G=10\Omega$ |
| Total gate charge | Q_g^* | - | 9.4 | - | nC | $V_{DD}=30V, I_D=8A$ |
| Gate-source charge | Q_{gs}^* | - | 1.8 | - | nC | $V_{GS}=10V$ |
| Gate-drain charge | Q_{gd}^* | - | 2.3 | - | nC | |

*Pulsed

● Body diode characteristics (Source-Drain)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|------------|------|------|------|------|---------------------|
| Forward Voltage | V_{SD}^* | - | - | 1.5 | V | $I_s=8A, V_{GS}=0V$ |

*Pulsed

●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics (I)

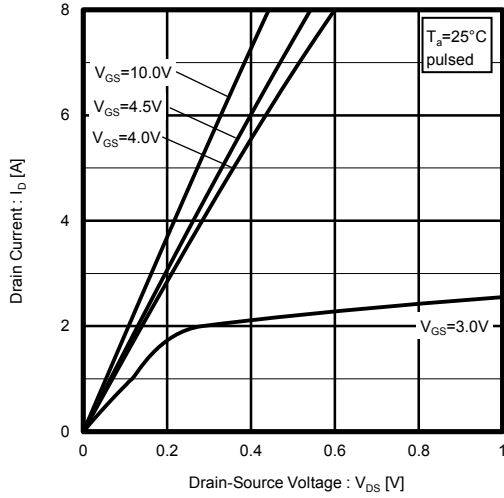


Fig.2 Typical Output Characteristics (II)

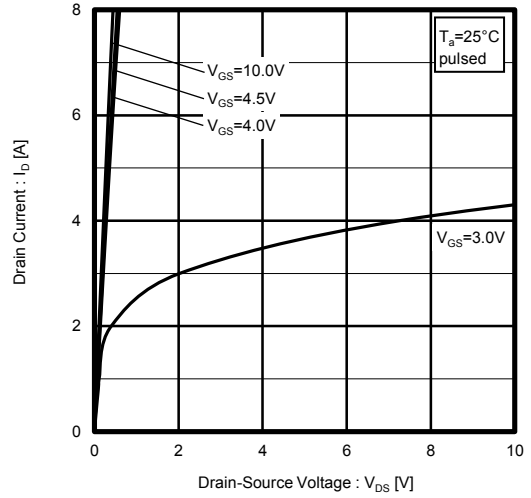


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

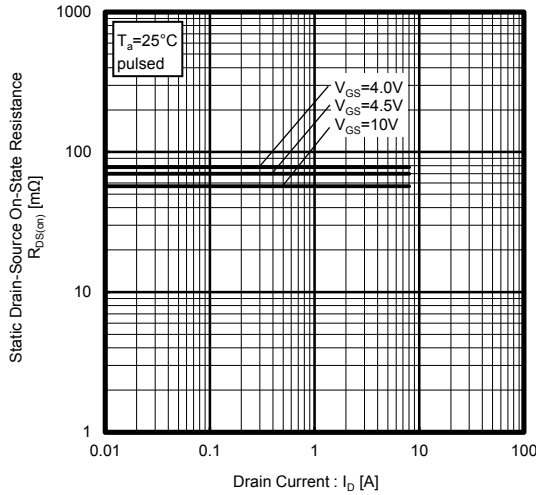


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

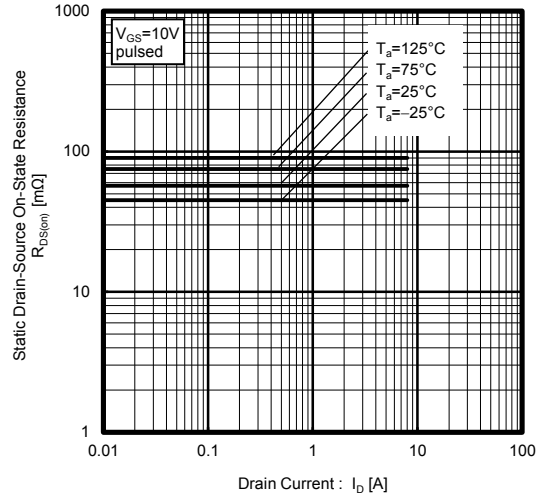


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

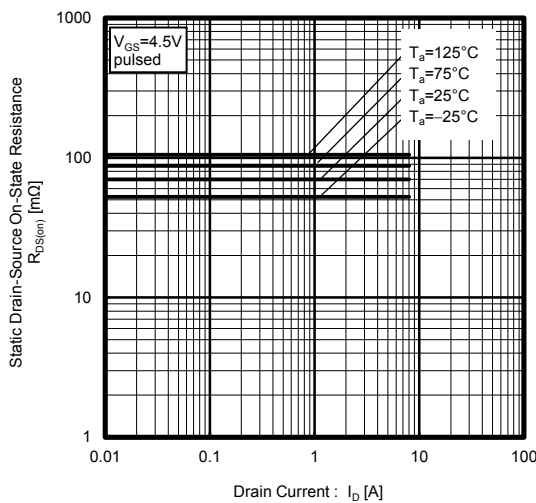


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

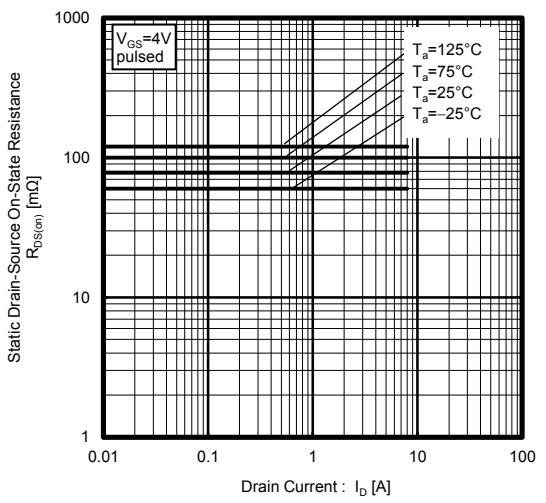


Fig.7 Forward Transfer Admittance vs. Drain Current

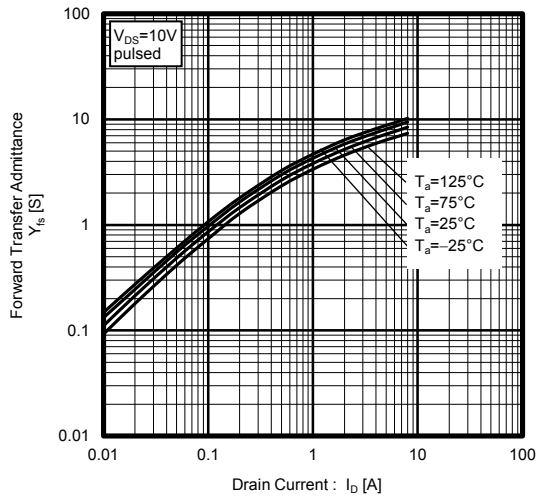


Fig.8 Typical Transfer Characteristics

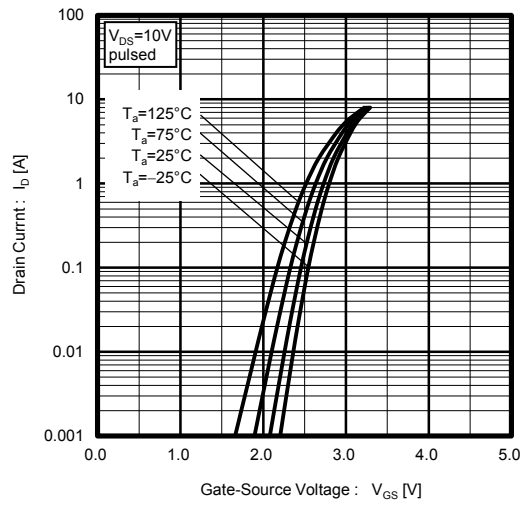


Fig.9 Source Current vs. Source-Drain Voltage

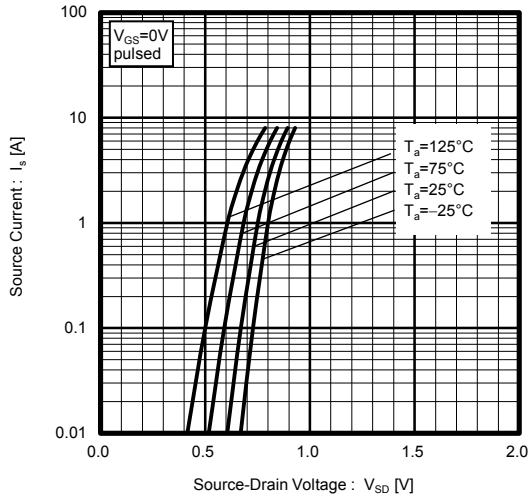


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

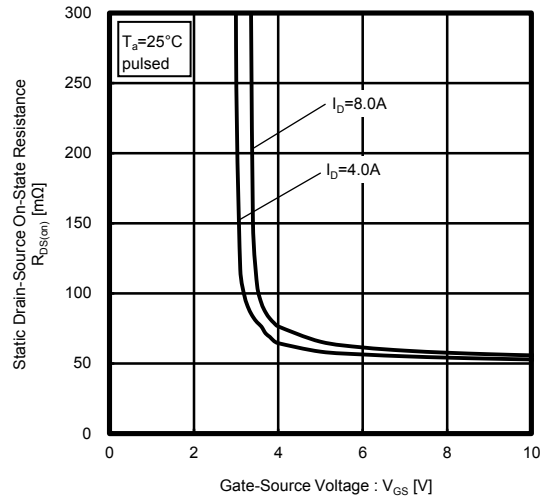


Fig.11 Switching Characteristics

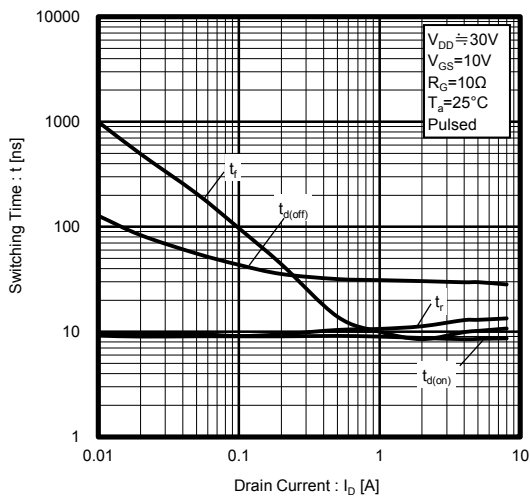


Fig.12 Dynamic Input Characteristics

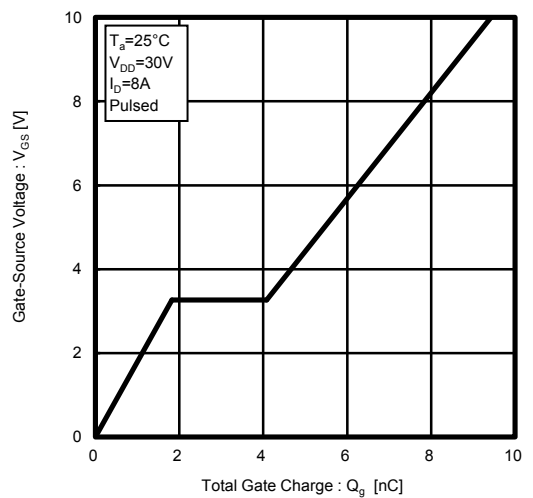


Fig.13 Typical Capacitance vs. Drain-Source Voltage

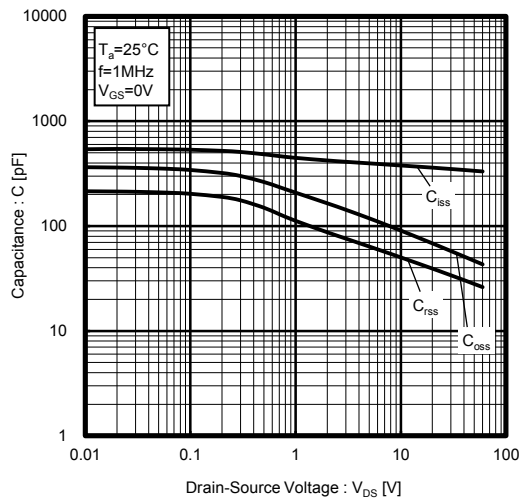


Fig.14 Maximum Safe Operating Area

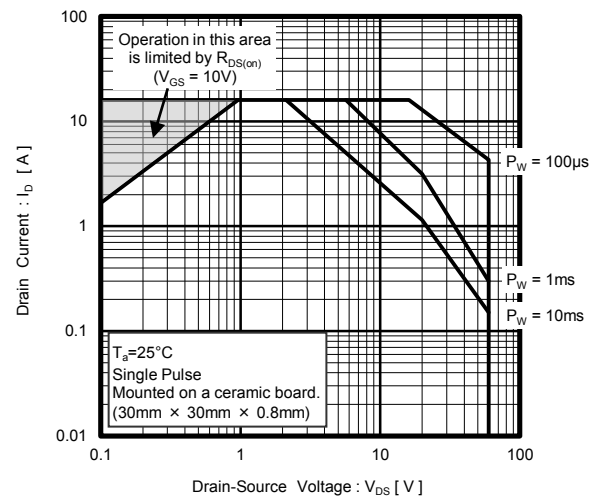
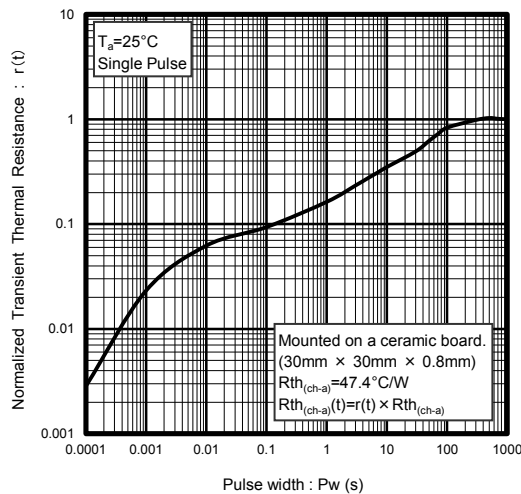


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width



● Measurement circuits

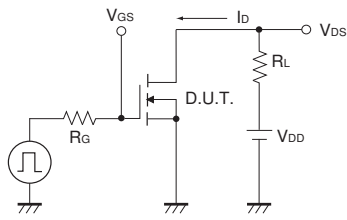


Fig.1-1 Switching Time Measurement Circuit

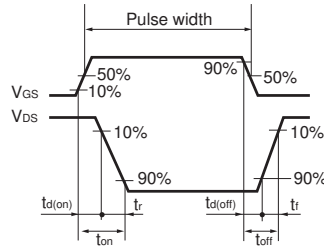


Fig.1-2 Switching Waveforms

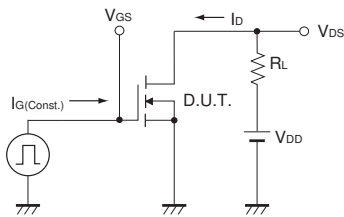


Fig.2-1 Gate Charge Measurement Circuit

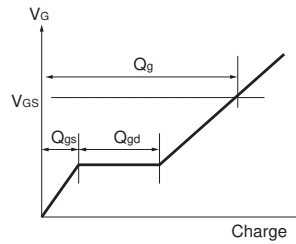


Fig.2-2 Gate Charge Waveform

Notes

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